SPECIFICATION

PART NO. : LT5244-41

2.0×5.0mm RECTANGULAR LED LAMP

Approved by	Checked by	Prepared by
Tung	*Yang*	*Haibo*

Description

This orange lamp is made with GaAsP/GaP chip and orange clear epoxy resin.

2.00

5.00

7.00

1.0 MAX.

24.0 MIN.

1.5 TYP.

2.54±0.1

0.5 SQUARE X 2

A   K
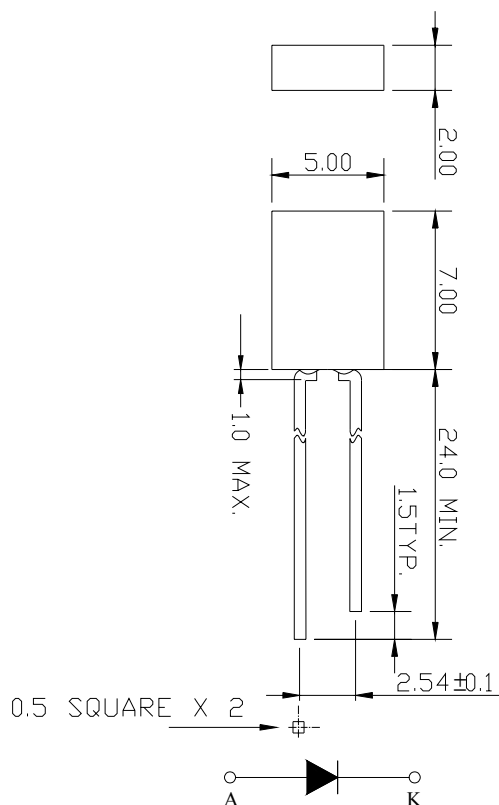
Notes:

1. All dimensions are in mm.

2. Tolerance is ± 0.25mm unless otherwise noted.

Description

Part No.	LED Chip		Lens Color
	Material	Emitting Color	
LT5244-41	GaAsP/GaP	Orange	Orange clear

Absolute Maximum Ratings at Ta=25

| Parameter	Symbol	Rating	Unit
Power Dissipation	PD	78	mW
Reverse Voltage	VR	5	V
D.C. Forward Current	If	30	mA
Reverse (Leakage) Current	Ir	100	μ A
Peak Current(1/10Duty Cycle,0.1ms Pulse Width.)	If(Peak)	100	mA
Operating Temperature Range	Topr	-25 to +85	
Storage Temperature Range	Tstg	-40 to +100	
Soldering Temperature(1.6mm from body)	Tsol	Dip Soldering : 260℃ for 5 sec. Hand Soldering : 350℃ for 3 sec.	

Electrical and Optical Characteristics:

| Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Luminous Intensity	Iv	If=20mA	4.2	10		mcd
Forward Voltage	Vf	If=20mA		2.1	2.6	V
Peak Wavelength	λp	If=20mA		635		nm
Dominant Wavelength	λd	If=20mA		626		nm
Reverse (Leakage) Current	Ir	Vr=5V			100	μA
Viewing Angle	2 1/2	If=20mA		90		deg
Spectrum Line Halfwidth	Δλ	If=20mA		35		nm

Notes:1. The datas tested by IS tester.
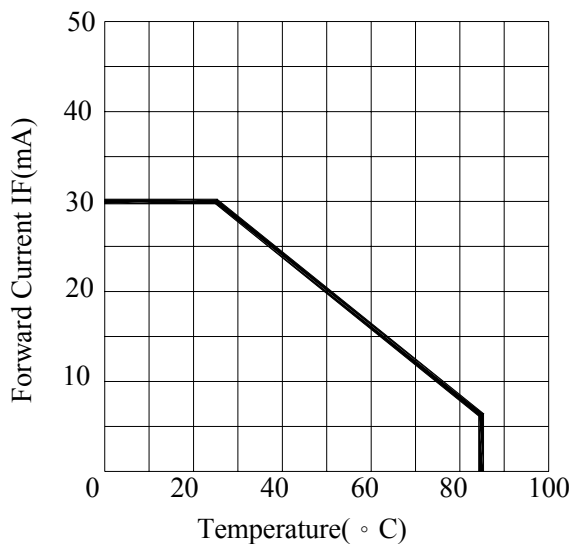
2. Customer's special requirements are also welcome.
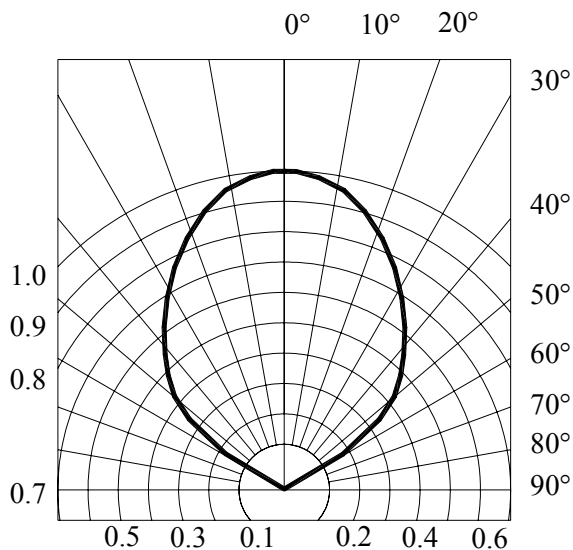
Typical Electrical / Optical Characteristics Curves :
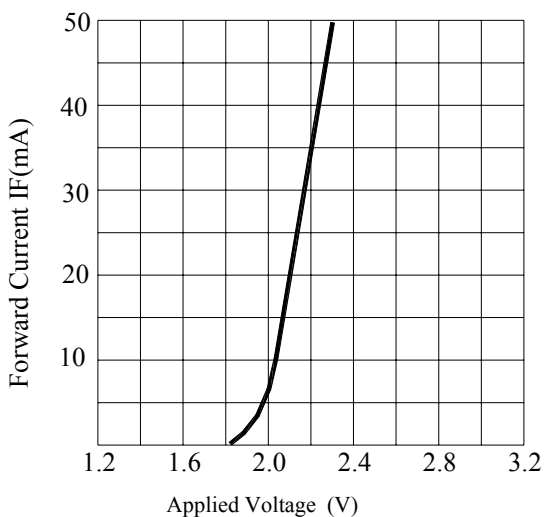
FORWARD CURRENT VS.APPLIED VOLTAGE
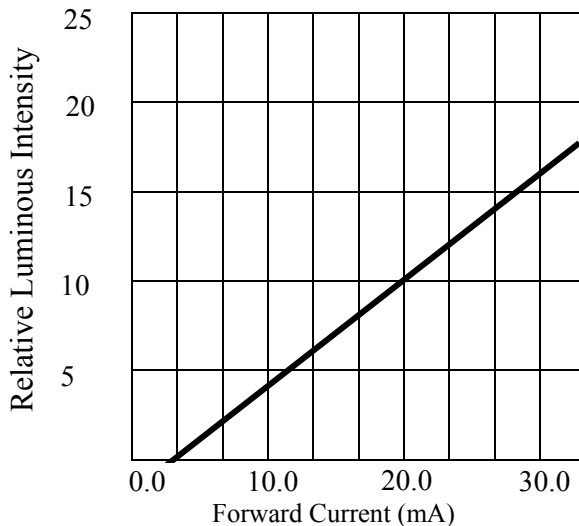
FORWARD CURRENT VS. LUMINOUS INTENSITY

FORWARD CURRENT VS. AMBIENT TEMPERATURE

RADIATION DIAGRAM

Precautions:

TAKE NOTE OF THE FOLLOWING IN USE OF LED

1. Temperature in use

    Since the light generated inside the LED needs to be emitted to outside efficiently, a resin with high light transparency is used; therefore, additives to improve the heat resistance or moisture resistance (silica gel , etc) which are used for semiconductor products such as transistors cannot be added to the resin.

    Consequently, the heat resistant ability of the resin used for LED is usually low; therefore, please be careful on the following during use.

    Avoid applying external force, stress, and excessive vibration to the resins and terminals at high temperature. The glass transition temperature of epoxy resin used for the LED is approximately 120-130   .

    At a temperature exceeding this limit, the coefficient of liner expansion of the resin doubles or more compared to that at normal temperature and the resin is softened.

    If external force or stress is applied at that time, it may cause a wire rupture.

2. Soldering

    Please be careful on the following at soldering.

    After soldering, avoided applying external force, stress, and excessive vibration until the products go to cooling process (normal temperature), <Same for products with terminal leads>

    (1) Soldering measurements:

        Distance between melted solder side to bottom of resin shall be 1.6mm or longer.

    (2) Dip soldering :

        Pre-heat: 90   max. (Backside of PCB), Within 60 seconds.

        Solder bath: 260±5   (Solder temperature), Within 5 seconds.

    (3) Hand soldering: 350   max. (Temperature of soldering iron tip), Within 3 seconds.

3. Insertion

    Pitch of the LED leads and pitch of mounting holes need to be same.

4. Others

    Since the heat resistant ability of the LED resin is low, SMD components are used on the same PCB, please mount the LED after adhesive baking process for SMD components. In case adhesive baking is done after LED lamp insertion due to a production process reason, make sure not to apply external force, stress, and excessive vibration to the LED and follow the conditions below.
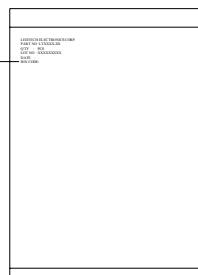
    Baking temperature: 120   max.   Baking time: Within 60 seconds.

    If soldering is done sequentially after the adhesive baking, please perform the soldering after cooling down the LED to normal temperature.
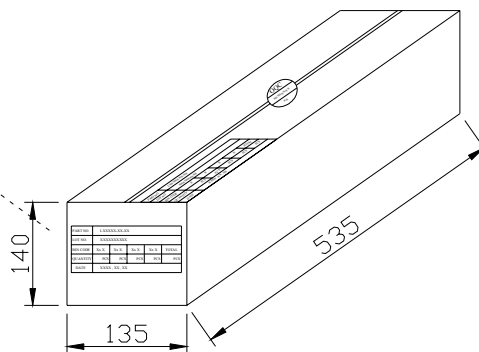
ENCASED TYPE

PLASTIC PACKAGE
QUANTITY: 1000 PCS

LEDTECH ELECTRONICS CORP.
PART NO :LTXXXX-XX
Q'TY : PCS
LOT NO :XXXXXXXXX
DATE :
BIN CODE:

INNER BOX
QUANTITY: 10 PACKETS
TOTAL: 10,000 PCS

PART NO.	LXXXXX-XX-XX				
LOT NO.	XXXXXXXXXX				
BIN CODE	Xx X	Xx X	Xx X	Xx X	TOTAL
QUANTITY	PCS	PCS	PCS	PCS	PCS
DATE	XXXX , XX , XX				

140
535
135

OUTER CARTON
QUANTITY: 4 BOX
TOTAL: 40,000 PCS

C/T NO. 箱　號	XX
PART NO. 料　號	LXXXXX-XX-XX
QUANTITY 數　量	PCS
N.W. 淨　重	KGS
G.W. 毛　重	KGS
REMARK 備　註	

320
550
295